

DATA SHEET

BF1202; BF1202R; BF1202WR N-channel dual-gate PoLo MOS-FETs

Product specification
Supersedes data of 2000 Mar 29

2010 Sep 16



N-channel dual-gate PoLo MOS-FETs BF1202; BF1202R; BF1202WR

FEATURES

- Short channel transistor with high forward transfer admittance to input capacitance ratio
- Low noise gain controlled amplifier
- Partly internal self-biasing circuit to ensure good cross-modulation performance during AGC and good DC stabilization.

APPLICATIONS

- VHF and UHF applications with 3 to 9 V supply voltage, such as digital and analogue television tuners and professional communications equipment.

DESCRIPTION

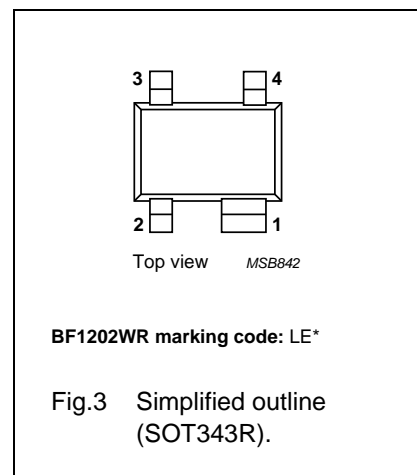
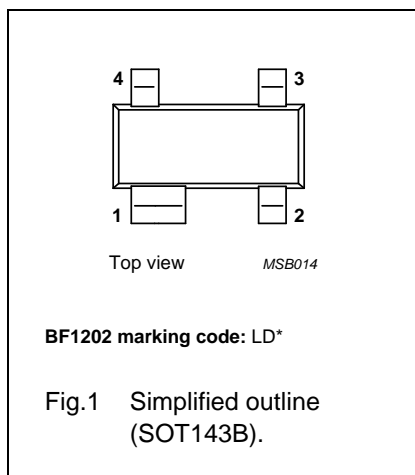
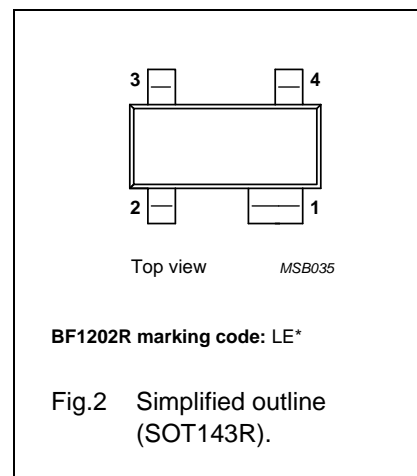
Enhancement type N-channel field-effect transistor with source and substrate interconnected. Integrated diodes between gates and source protect against excessive input voltage surges. The BF1202, BF1202R and BF1202WR are encapsulated in the SOT143B, SOT143R and SOT343R plastic packages respectively.

PINNING

PIN	DESCRIPTION
1	source
2	drain
3	gate 2
4	gate 1

Marking code legend:

- * = - : made in Hong Kong
- * = p : made in Hong Kong
- * = t : made in Malaysia



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DS}	drain-source voltage		–	–	10	V
I_D	drain current		–	–	30	mA
P_{tot}	total power dissipation		–	–	200	mW
$ y_{fs} $	forward transfer admittance		25	30	40	mS
C_{ig1-ss}	input capacitance at gate 1		–	1.7	2.2	pF
C_{rss}	reverse transfer capacitance	$f = 1 \text{ MHz}$	–	15	30	fF
F	noise figure	$f = 800 \text{ MHz}$	–	1.1	1.8	dB
X_{mod}	cross-modulation	input level for $k = 1\%$ at 40 dB AGC	100	105	–	dB μ V
T_j	operating junction temperature		–	–	150	°C

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling.

N-channel dual-gate PoLo MOS-FETs

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

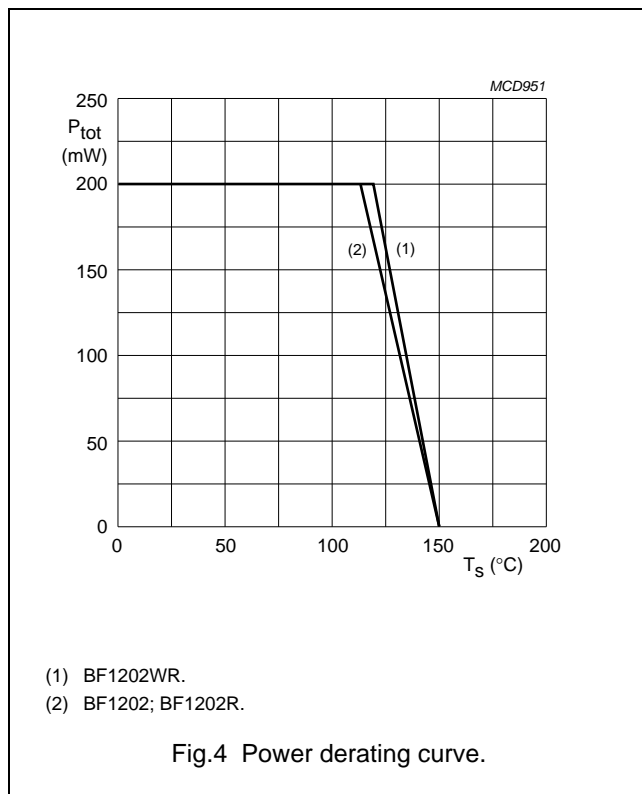
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage		–	10	V
I_D	drain current		–	30	mA
I_{G1}	gate 1 current		–	±10	mA
I_{G2}	gate 2 current		–	±10	mA
P_{tot}	total power dissipation				
	BF1202; BF1202R	$T_s \leq 113\text{ °C}$; note 1	–	200	mW
	BF1202WR	$T_s \leq 119\text{ °C}$; note 1	–	200	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–	150	°C

Note

- T_s is the temperature of the soldering point of the source lead.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point		
	BF1202; BF1202R	185	K/W
	BF1202WR	155	K/W



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STATIC CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{G1-S} = V_{G2-S} = 0$; $I_D = 10\text{ }\mu\text{A}$	10	–	V
$V_{(BR)G1-SS}$	gate 1-source breakdown voltage	$V_{G2-S} = V_{DS} = 0$; $I_{G1-S} = 10\text{ mA}$	6	–	V
$V_{(BR)G2-SS}$	gate 2-source breakdown voltage	$V_{G1-S} = V_{DS} = 0$; $I_{G2-S} = 10\text{ mA}$	6	–	V
$V_{(F)S-G1}$	forward source-gate 1 voltage	$V_{G2-S} = V_{DS} = 0$; $I_{S-G1} = 10\text{ mA}$	0.5	1.5	V
$V_{(F)S-G2}$	forward source-gate 2 voltage	$V_{G1-S} = V_{DS} = 0$; $I_{S-G2} = 10\text{ mA}$	0.5	1.5	V
$V_{G1-S(th)}$	gate 1-source threshold voltage	$V_{G2-S} = 4\text{ V}$; $V_{DS} = 5\text{ V}$; $I_D = 100\text{ }\mu\text{A}$	0.3	1.0	V
$V_{G2-S(th)}$	gate 2-source threshold voltage	$V_{G1-S} = 5\text{ V}$; $V_{DS} = 5\text{ V}$; $I_D = 100\text{ }\mu\text{A}$	0.3	1.2	V
I_{DSX}	drain-source current	$V_{G2-S} = 4\text{ V}$; $V_{DS} = 5\text{ V}$; $R_{G1} = 120\text{ k}\Omega$; note 1	8	16	mA
I_{G1-SS}	gate 1 cut-off current	$V_{G2-S} = V_{DS} = 0$; $V_{G1-S} = 5\text{ V}$	–	50	nA
I_{G2-SS}	gate 2 cut-off current	$V_{G1-S} = V_{DS} = 0$; $V_{G2-S} = 4\text{ V}$	–	20	nA

Note

- R_{G1} connects G_1 to $V_{GG} = 5\text{ V}$.

DYNAMIC CHARACTERISTICS

Common source; $T_{amb} = 25\text{ °C}$; $V_{G2-S} = 4\text{ V}$; $V_{DS} = 5\text{ V}$; $I_D = 12\text{ mA}$; unless otherwise specified.

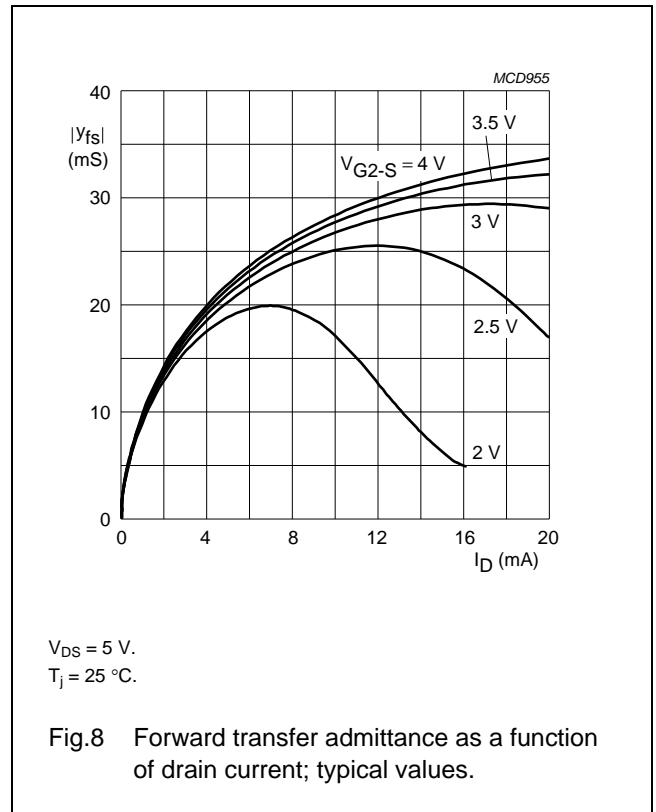
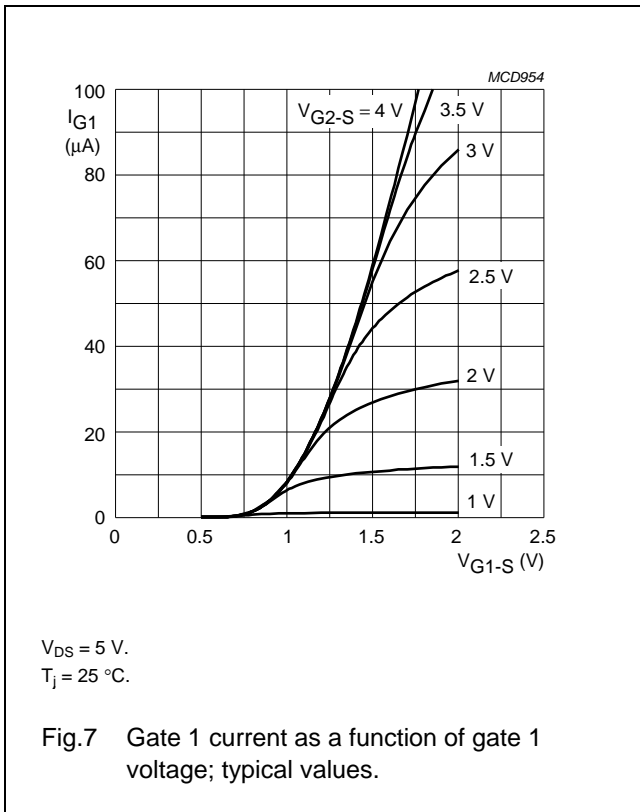
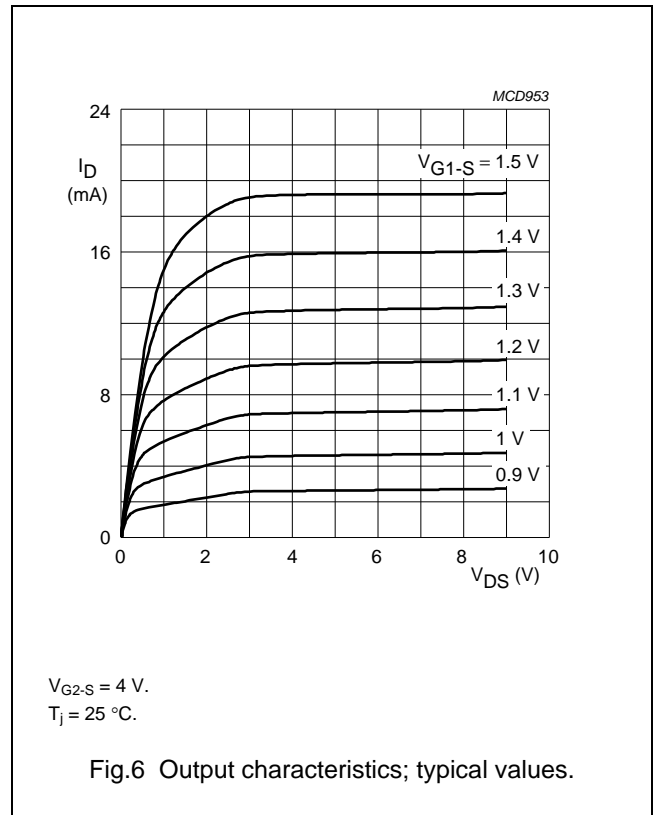
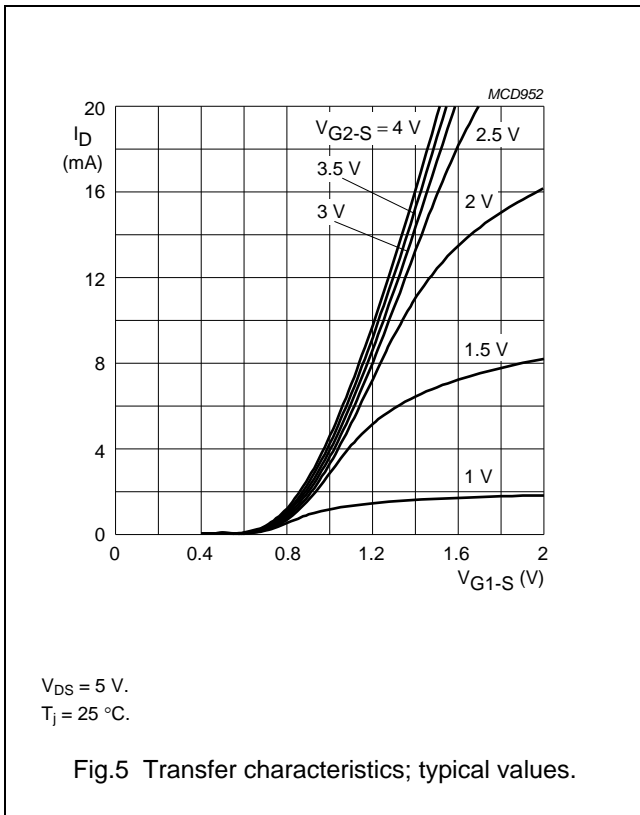
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$ y_{fs} $	forward transfer admittance	pulsed; $T_j = 25\text{ °C}$	25	30	40	mS
C_{ig1-ss}	input capacitance at gate 1	$f = 1\text{ MHz}$	–	1.7	2.2	pF
C_{ig2-ss}	input capacitance at gate 2	$f = 1\text{ MHz}$	–	1	–	pF
C_{oss}	output capacitance	$f = 1\text{ MHz}$	–	0.85	–	pF
C_{rss}	reverse transfer capacitance	$f = 1\text{ MHz}$	–	15	30	fF
F	noise figure	$f = 10.7\text{ MHz}$; $G_S = 20\text{ mS}$; $B_S = 0$	–	9	11	dB
		$f = 400\text{ MHz}$; $Y_S = Y_{S\text{ opt}}$	–	0.9	1.5	dB
		$f = 800\text{ MHz}$; $Y_S = Y_{S\text{ opt}}$	–	1.1	1.8	dB
G_{tr}	power gain	$f = 200\text{ MHz}$; $G_S = 2\text{ mS}$; $B_S = B_{S\text{ opt}}$; $G_L = 0.5\text{ mS}$; $B_L = B_{L\text{ opt}}$	–	34.5	–	dB
		$f = 400\text{ MHz}$; $G_S = 2\text{ mS}$; $B_S = B_{S\text{ opt}}$; $G_L = 1\text{ mS}$; $B_L = B_{L\text{ opt}}$	–	30.5	–	dB
		$f = 800\text{ MHz}$; $G_S = 3.3\text{ mS}$; $B_S = B_{S\text{ opt}}$; $G_L = 1\text{ mS}$; $B_L = B_{L\text{ opt}}$	–	26.5	–	dB
X_{mod}	cross-modulation	input level for $k = 1\%$; $f_w = 50\text{ MHz}$; $f_{unw} = 60\text{ MHz}$; note 1				
		at 0 dB AGC	90	–	–	dB μ V
		at 10 dB AGC	–	92	–	dB μ V
	at 40 dB AGC	100	105	–	dB μ V	

Note

- Measured in Fig.21 test circuit.

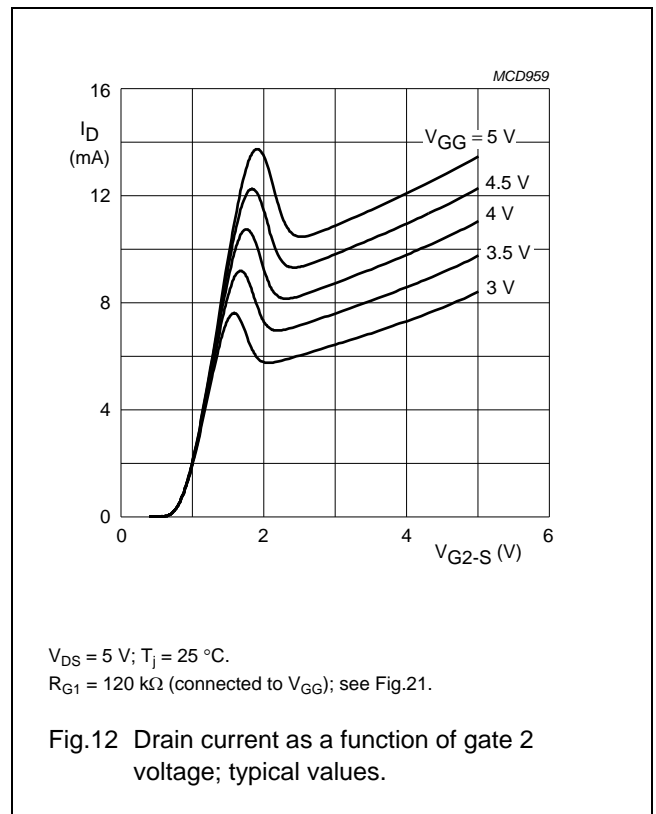
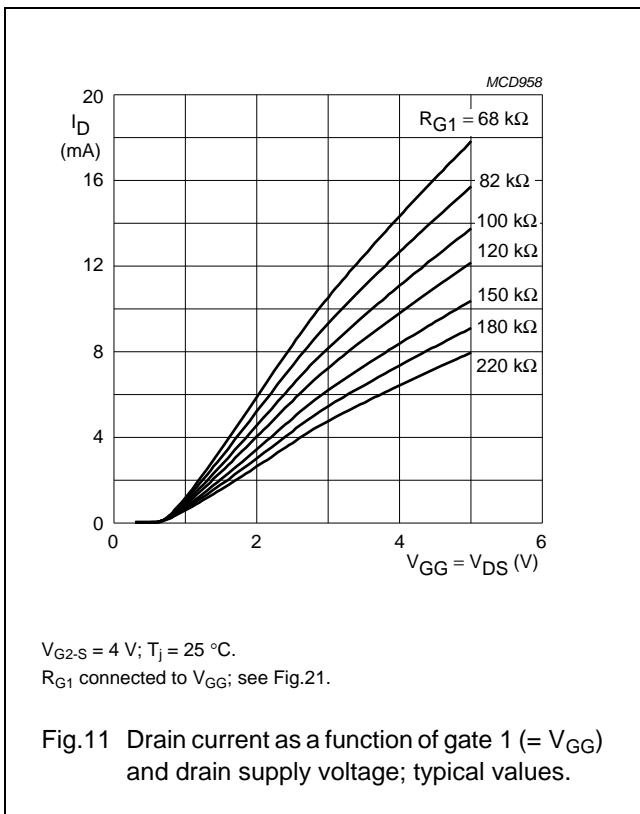
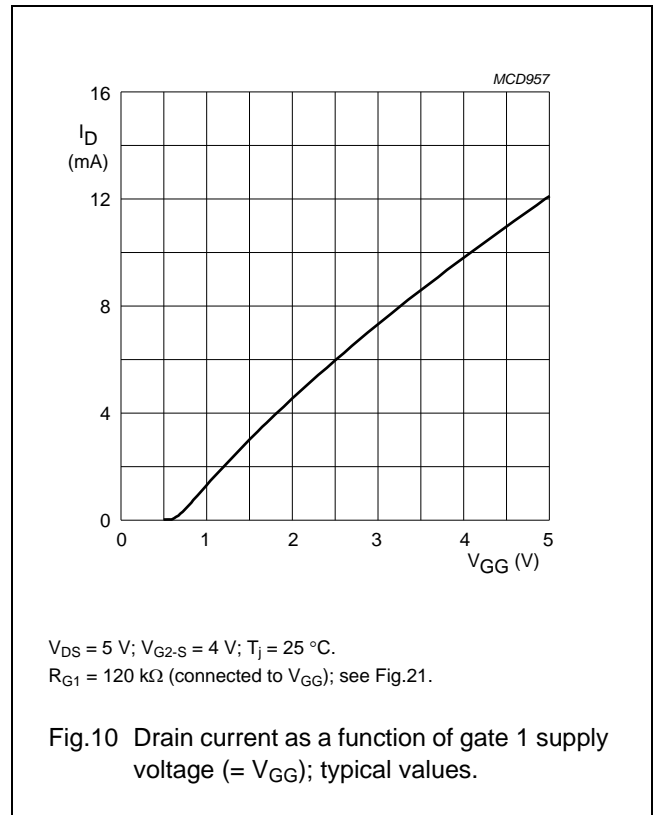
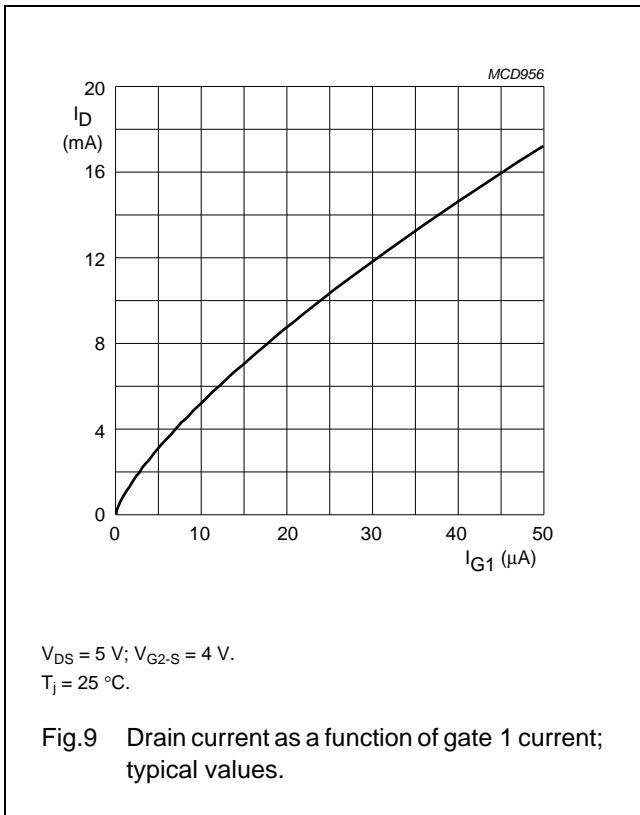
N-channel dual-gate PoLo MOS-FETs

BF1202; BF1202R; BF1202WR



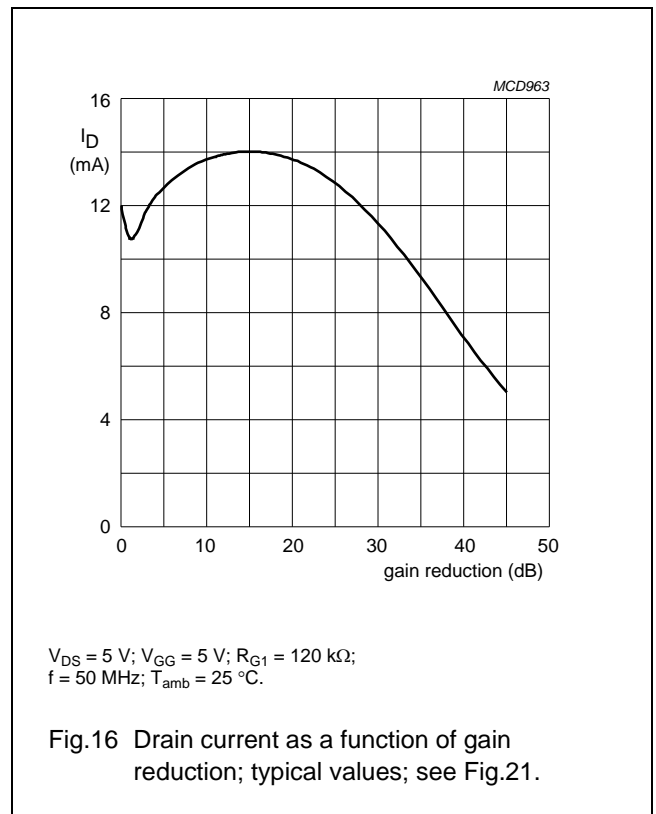
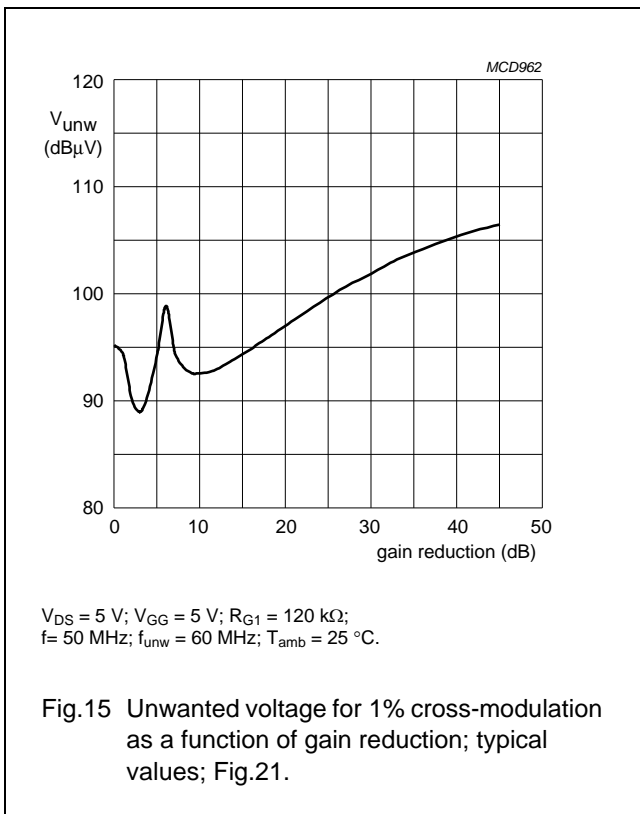
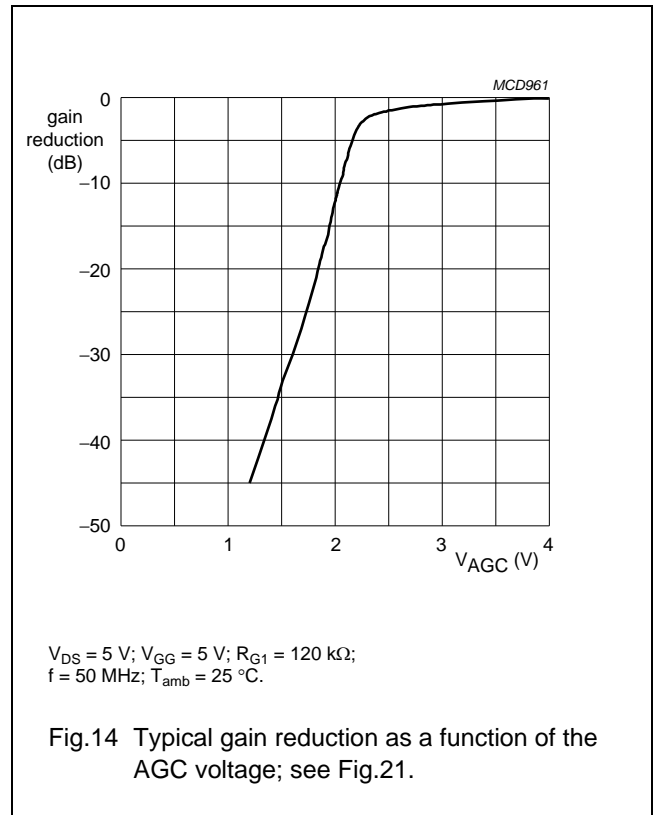
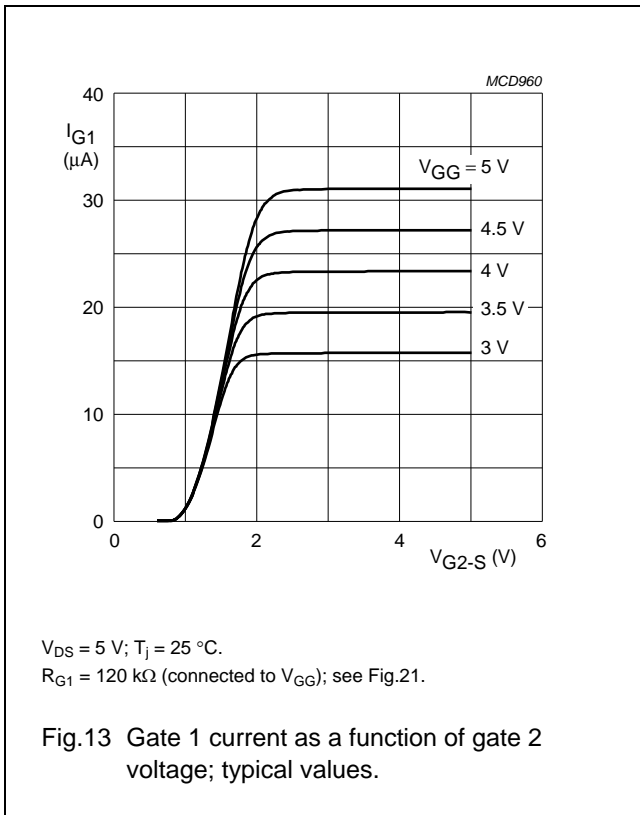
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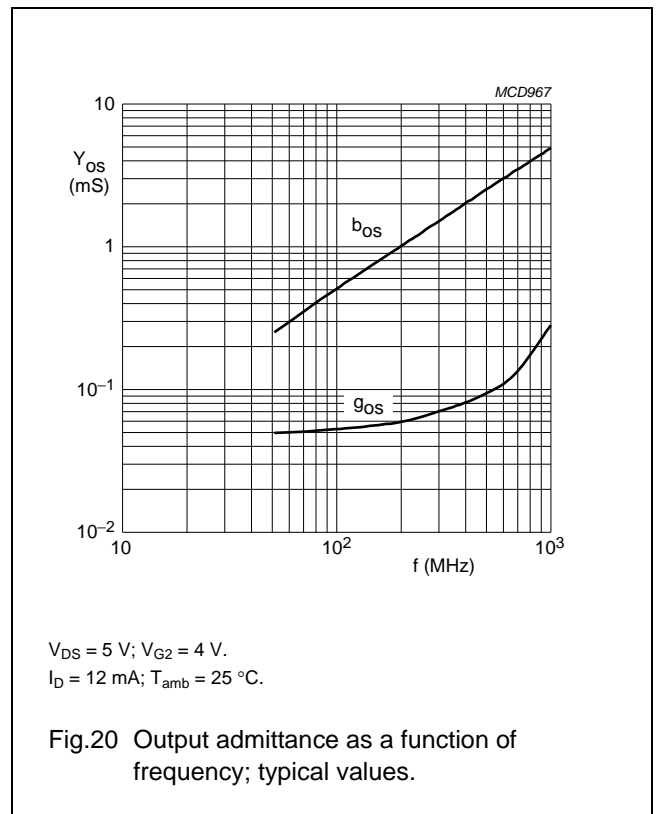
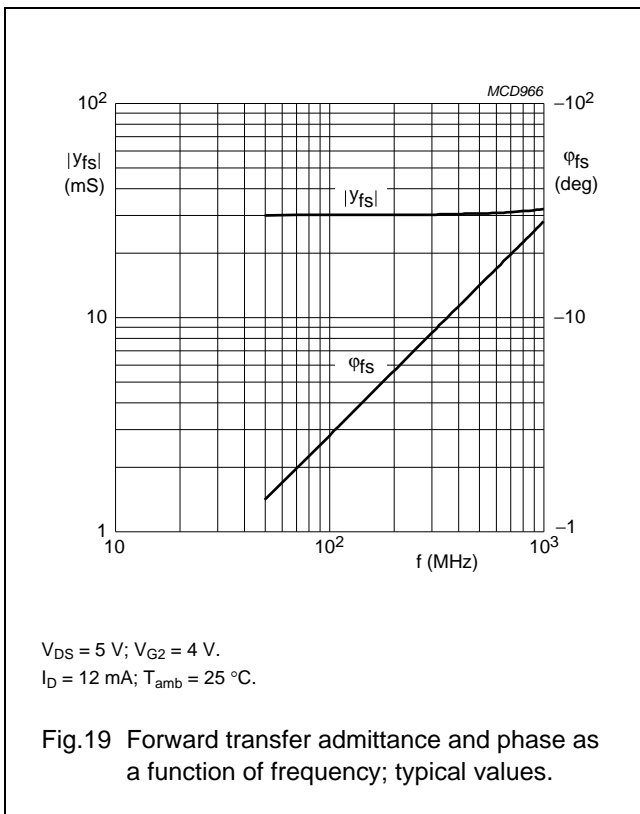
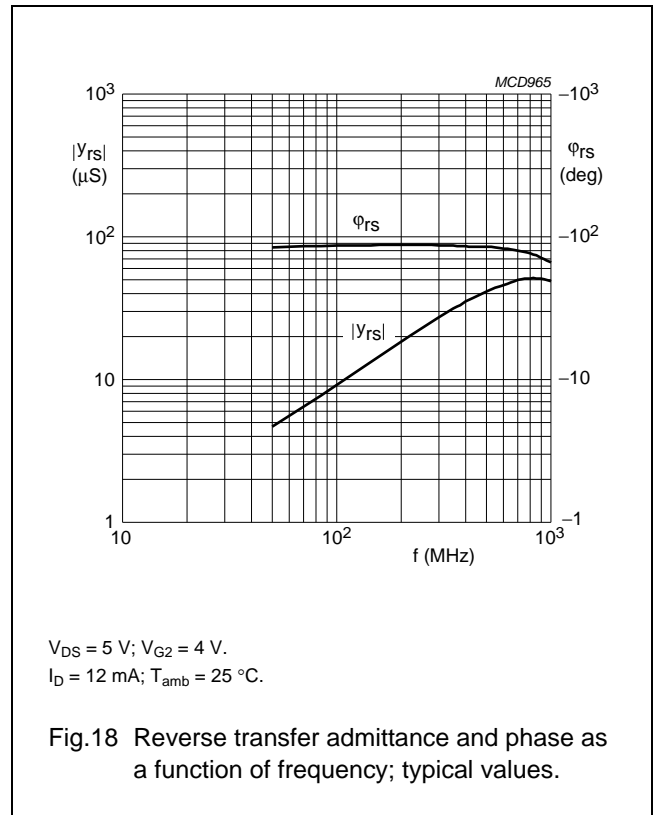
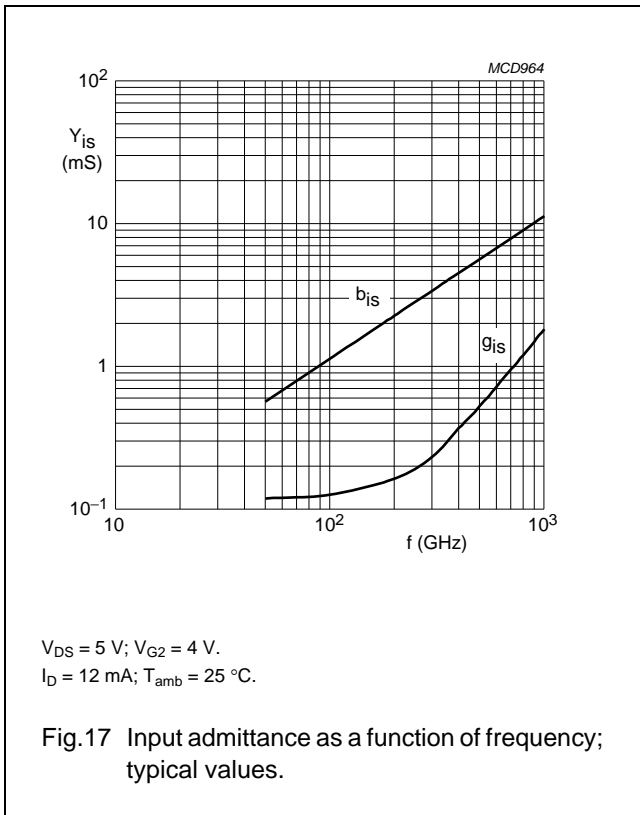
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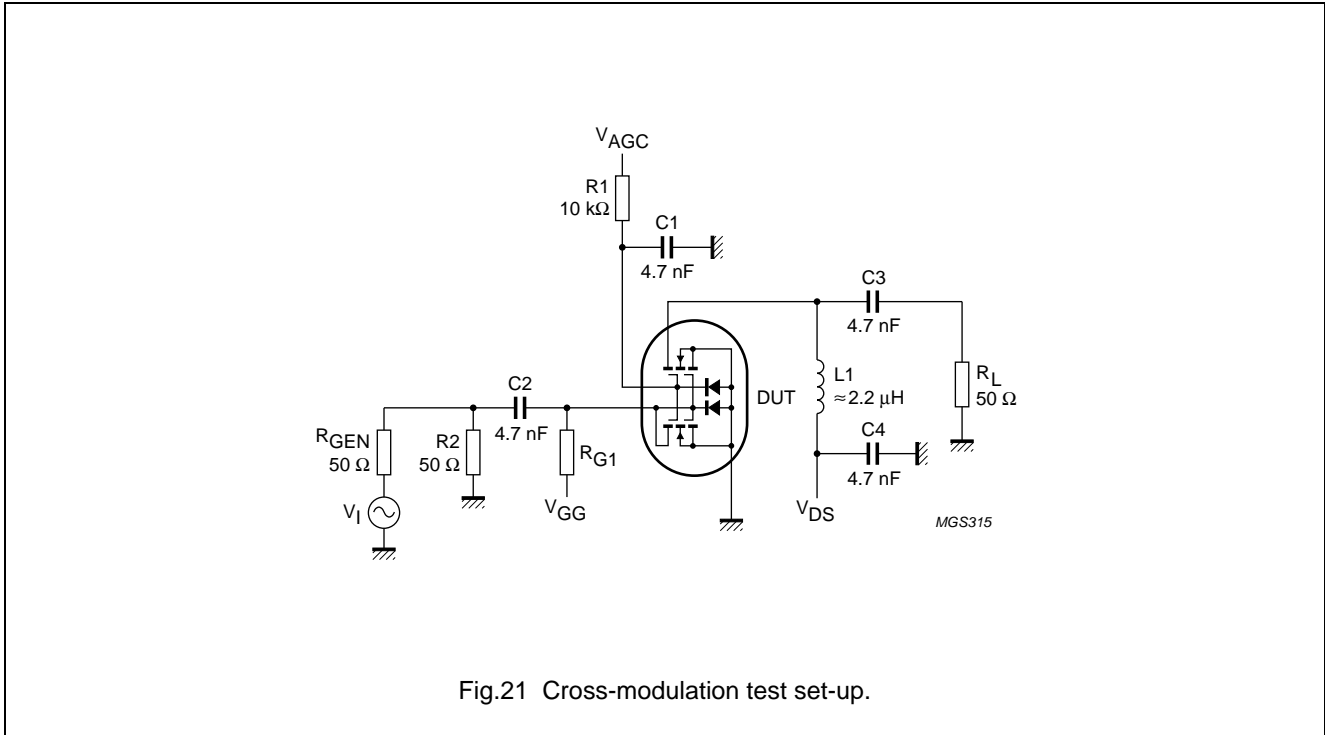


Fig.21 Cross-modulation test set-up.

Table 1 Scattering parameters: $V_{DS} = 5\ \text{V}$; $V_{G2-S} = 4\ \text{V}$; $I_D = 12\ \text{mA}$; $T_{amb} = 25\ \text{°C}$

f (MHz)	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)
50	0.988	-3.26	2.989	176.2	0.0005	92.6	0.995	-1.50
100	0.988	-6.52	3.017	172.5	0.0009	88.0	0.995	-3.01
200	0.984	-12.99	2.990	165.0	0.0018	82.5	0.994	-5.95
300	0.977	-19.39	2.949	157.6	0.0027	78.2	0.992	-8.86
400	0.965	-25.65	2.913	150.3	0.0036	75.4	0.990	-11.79
500	0.951	-31.76	2.853	143.2	0.0039	71.8	0.988	-14.65
600	0.936	-37.68	2.793	136.3	0.0042	69.9	0.986	-17.41
700	0.919	-43.42	2.727	129.5	0.0044	68.9	0.984	-20.10
800	0.903	-48.94	2.664	123.0	0.0043	68.5	0.980	-22.69
900	0.887	-54.25	2.593	116.7	0.0041	70.7	0.975	-25.27
1000	0.870	-59.34	2.518	110.5	0.0038	72.4	0.970	-27.90

Table 2 Noise data: $V_{DS} = 5\ \text{V}$; $V_{G2-S} = 4\ \text{V}$; $I_D = 12\ \text{mA}$; $T_{amb} = 25\ \text{°C}$

f (MHz)	F _{min} (dB)	Γ _{opt}		R _n (Ω)
		(ratio)	(deg)	
400	0.9	0.805	28.5	50
800	1.1	0.725	47.2	40

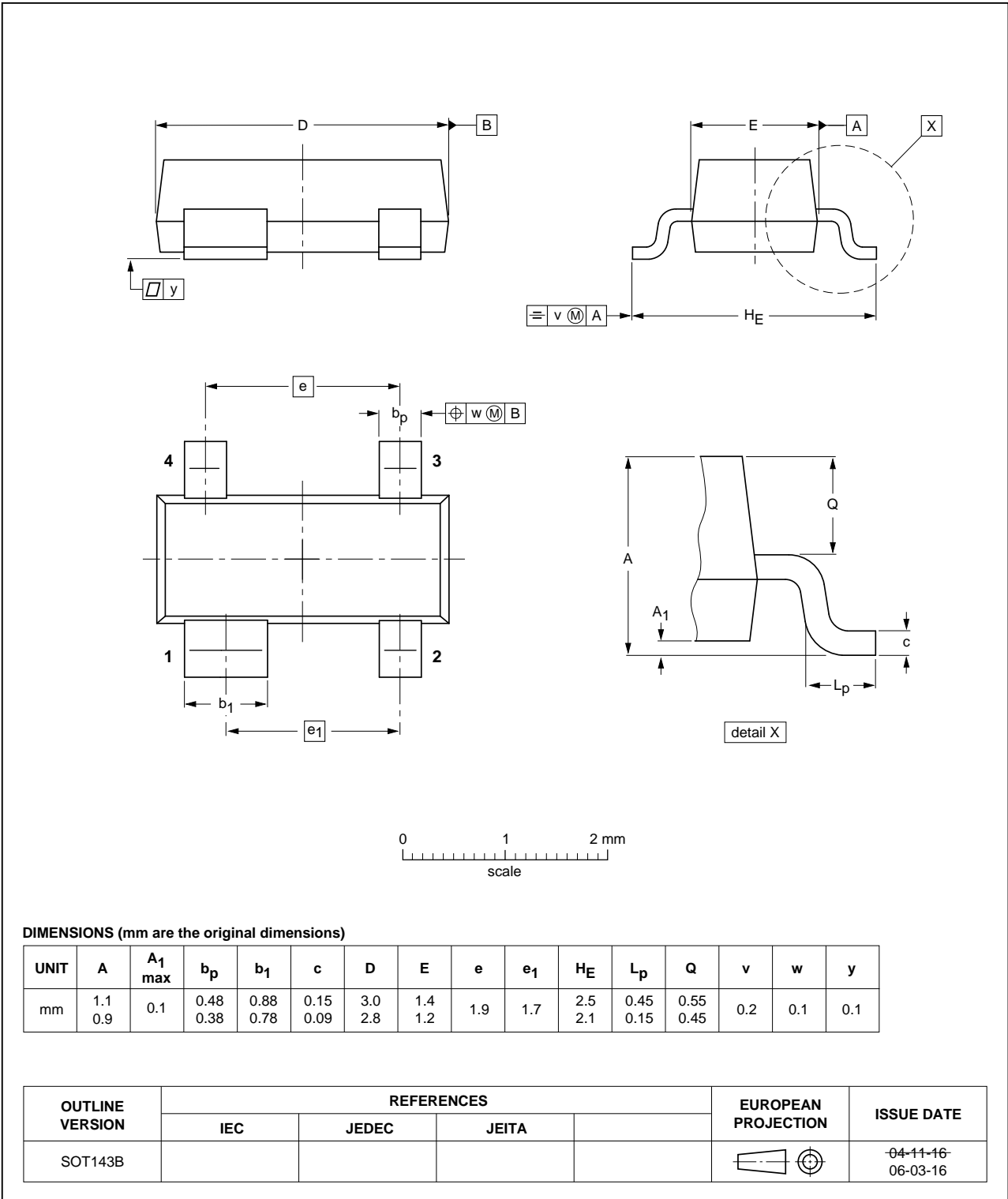
N-channel dual-gate PoLo MOS-FETs

BF1202; BF1202R; BF1202WR

PACKAGE OUTLINES

Plastic surface-mounted package; 4 leads

SOT143B

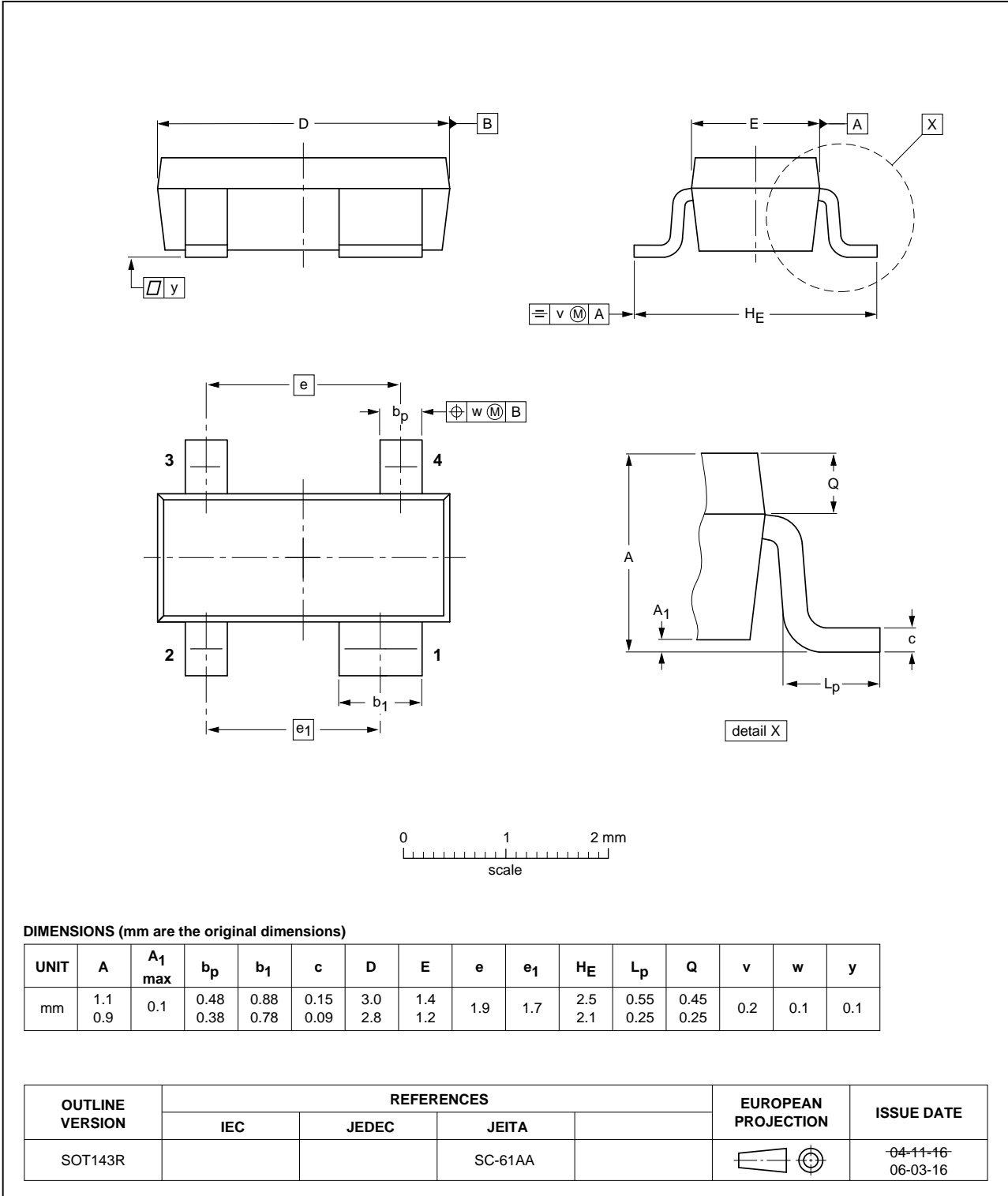


N-channel dual-gate PoLo MOS-FETs

BF1202; BF1202R; BF1202WR

Plastic surface-mounted package; reverse pinning; 4 leads

SOT143R

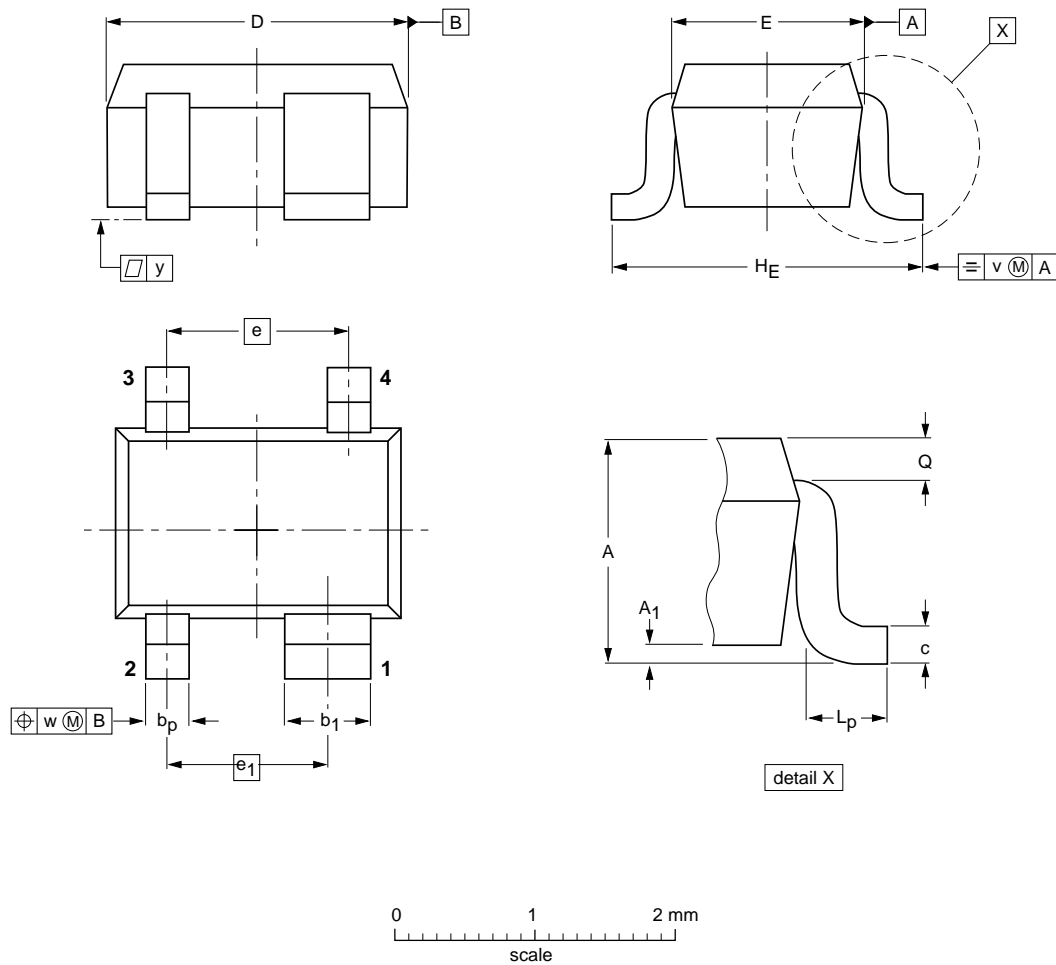


N-channel dual-gate PoLo MOS-FETs

BF1202; BF1202R; BF1202WR

Plastic surface-mounted package; reverse pinning; 4 leads

SOT343R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT343R						97-05-21 06-03-16

N-channel dual-gate PoLo MOS-FETs

BF1202; BF1202R; BF1202WR

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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